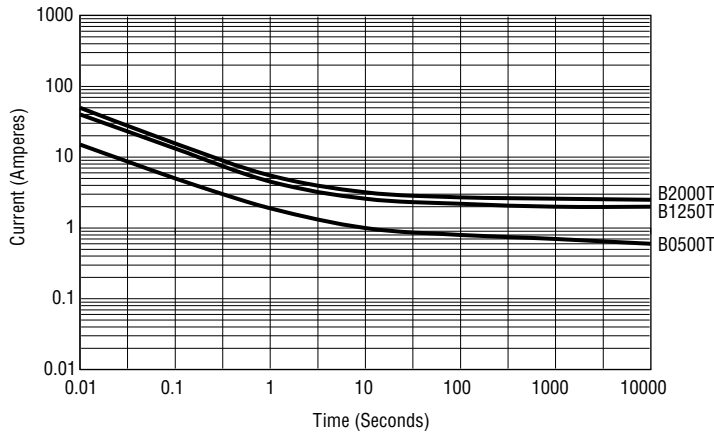
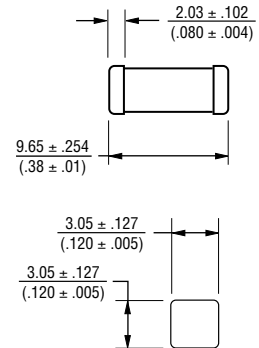


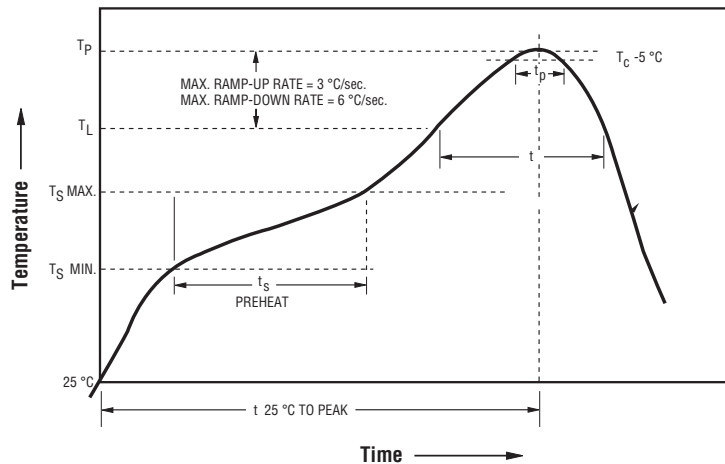
## Time/Current Characteristic Curve



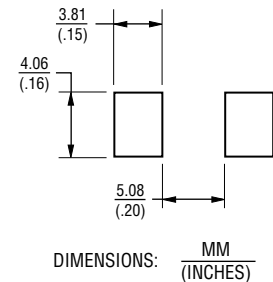
## Product Dimensions



## Solder Profile



## Recommended Pad Layout



DIMENSIONS:  $\frac{\text{MM}}{\text{(INCHES)}}$

## IR Reflow Profile

Reflow Parameter	Value
Minimum Preheat Temperature ( $T_{S\text{MIN}}$ )	130 °C
Maximum Preheat Temperature ( $T_{S\text{MAX}}$ )	170 °C
Preheat Time	60-180 seconds
$T_{S\text{MAX}}$ to $T_L$ Ramp-Up Rate	3 °C / second max.
Time above Temperature $T_L$ ( $t_L$ )	200 °C for 60-120 seconds
Peak Temperature ( $T_p$ )	240 °C max.
Time within 5 °C of Peak $T_p$	20-30 seconds
Ramp-Down Rate	6 °C / second. max.



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